

**MOSFET – N-Channel,
POWERTRENCH®****60 V, 50 A, 10.5 mΩ****FDD10AN06A0****Features**

- $R_{DS(on)} = 9.4 \text{ mΩ}$ (Typ.), $V_{GS} = 10 \text{ V}$, $I_D = 50 \text{ A}$
- $Q_g(\text{tot}) = 28 \text{ nC}$ (Typ.), $V_{GS} = 10 \text{ V}$
- Low Miller Charge
- Low Qrr Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- This Device is Pb-Free, Halide Free and is RoHS Compliant

Applications

- Motor / Body Load Control
- ABS Systems
- Powertrain Management
- Injection Systems
- DC-DC Converters and Off-line UPS
- Distributed Power Architectures and VRMs
- Primary Switch for 12 V and 24 V Systems

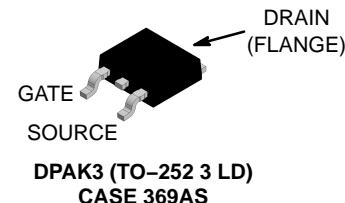
MOSFET MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Ratings | Unit |
|-------------------|---|----------------------|---------------------|
| V_{DSS} | Drain to Source Voltage | 60 | V |
| V_{GS} | Gate to Source Voltage | ± 20 | V |
| I_D | Drain Current Continuous ($T_C < 115^\circ\text{C}$, $V_{GS} = 10 \text{ V}$) Continuous ($T_{amb} = 25^\circ\text{C}$, $V_{GS} = 10 \text{ V}$, $R_{0JA} = 52^\circ\text{C}/\text{W}$) Pulsed | 50 11 Figure 4 | A |
| E_{AS} | Single Pulse Avalanche Energy (Note 1) | 429 | mJ |
| P_D | Power Dissipation | 135 | W |
| | Derate above 25°C | 0.9 | W/ $^\circ\text{C}$ |
| T_J , T_{STG} | Operating and Storage Temperature | -55 to 175 | $^\circ\text{C}$ |

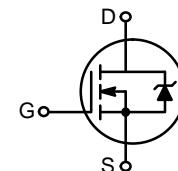
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Starting $T_J = 25^\circ\text{C}$, $L = 8.58 \text{ mH}$, $I_{AS} = 10 \text{ A}$.

| V_{DSS} | $R_{DS(on)}$ MAX | I_D MAX |
|-----------|------------------|-----------|
| 60 V | 10.5 mΩ @ 10 V | 50 A |

**MARKING DIAGRAM**

$\&Z$ = Assembly Plant Code
 $\&3$ = 3-Digit Date Code
 $\&K$ = 2-Digits Lot Run Traceability Code
 FDD10AN06A0 = Specific Device Code

**N-Channel MOSFET****ORDERING INFORMATION**

See detailed ordering and shipping information on page 12 of this data sheet.

FDD10AN06A0

THERMAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Ratings | Unit |
|-----------------------|---|---------|---------------------------|
| $R_{\theta\text{JC}}$ | Thermal Resistance Junction to Case, TO-252 | 1.11 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta\text{JA}}$ | Thermal Resistance Junction to Ambient, TO-252 | 100 | |
| $R_{\theta\text{JA}}$ | Thermal Resistance Junction to Ambient, TO-252, 1 in ² Copper Pad Area | 52 | $^\circ\text{C}/\text{W}$ |

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit |
|--------|-----------|----------------|-----|-----|-----|------|
|--------|-----------|----------------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | | |
|-------------------|-----------------------------------|--|----|---|-----------|---------------|
| B_{VDSS} | Drain to Source Breakdown Voltage | $I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}$ | 60 | — | — | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$ | — | — | 1 | μA |
| | | $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, T_C = 150^\circ\text{C}$ | — | — | 250 | |
| I_{GSS} | Gate to Source Leakage Current | $V_{GS} = \pm 20 \text{ V}$ | — | — | ± 100 | nA |

ON CHARACTERISTICS

| | | | | | | |
|---------------------|----------------------------------|--|---|--------|--------|----------|
| $V_{GS(\text{TH})}$ | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$ | 2 | — | 4 | V |
| $R_{DS(\text{on})}$ | Drain to Source On Resistance | $I_D = 50 \text{ A}, V_{GS} = 10 \text{ V}$ | — | 0.0094 | 0.0105 | Ω |
| | | $I_D = 50 \text{ A}, V_{GS} = 10 \text{ V}, T_J = 175^\circ\text{C}$ | — | 0.020 | 0.023 | |

DYNAMIC CHARACTERISTICS

| | | | | | | |
|---------------------|----------------------------------|--|---|------|-----|----|
| C_{iss} | Input Capacitance | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | — | 1840 | — | pF |
| C_{oss} | Output Capacitance | | — | 340 | — | pF |
| C_{rss} | Reverse Transfer Capacitance | | — | 110 | — | pF |
| $Q_{\text{g(TOT)}}$ | Total Gate Charge at 10 V | $V_{GS} = 0 \text{ V} \text{ to } 10 \text{ V}, V_{DD} = 30 \text{ V}, I_D = 50 \text{ A}, I_g = 1.0 \text{ mA}$ | — | 28 | 37 | nC |
| $Q_{\text{g(TH)}}$ | Threshold Gate Charge | $V_{GS} = 0 \text{ V} \text{ to } 2 \text{ V}, V_{DD} = 30 \text{ V}, I_D = 50 \text{ A}, I_g = 1.0 \text{ mA}$ | — | 3.5 | 4.6 | nC |
| Q_{gs} | Gate to Source Gate Charge | $V_{DD} = 30 \text{ V}, I_D = 50 \text{ A}, I_g = 1.0 \text{ mA}$ | — | 9.8 | — | nC |
| Q_{gs2} | Gate Charge Threshold to Plateau | | — | 6.4 | — | nC |
| Q_{gd} | Gate to Drain "Miller" Charge | | — | 7.8 | — | nC |

SWITCHING CHARACTERISTICS ($V_{GS} = 10 \text{ V}$)

| | | | | | | |
|---------------------|---------------------|--|---|----|-----|----|
| t_{ON} | Turn-On Time | $V_{DD} = 30 \text{ V}, I_D = 50 \text{ A}$ $V_{GS} = 10 \text{ V}, R_{GS} = 10 \Omega$ | — | — | 131 | ns |
| $t_{\text{d(ON)}}$ | Turn-On Delay Time | | — | 8 | — | ns |
| t_r | Rise Time | | — | 79 | — | ns |
| $t_{\text{d(OFF)}}$ | Turn-Off Delay Time | | — | 32 | — | ns |
| t_f | Fall Time | | — | 32 | — | ns |
| t_{OFF} | Turn-Off Time | | — | — | 97 | ns |

DRAIN-SOURCE DIODE CHARACTERISTICS

| | | | | | | |
|-----------------|-------------------------------|---|---|---|------|----|
| V_{SD} | Source to Drain Diode Voltage | $I_{SD} = 50 \text{ A}$ | — | — | 1.25 | V |
| | | $I_{SD} = 25 \text{ A}$ | — | — | 1.0 | V |
| t_{rr} | Reverse Recovery Time | $I_{SD} = 50 \text{ A}, dI_{SD}/dt = 100 \text{ A}/\mu\text{s}$ | — | — | 27 | ns |
| Q_{RR} | Reverse Recovered Charge | $I_{SD} = 50 \text{ A}, dI_{SD}/dt = 100 \text{ A}/\mu\text{s}$ | — | — | 23 | nC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

FDD10AN06A0

TYPICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$, unless otherwise noted)

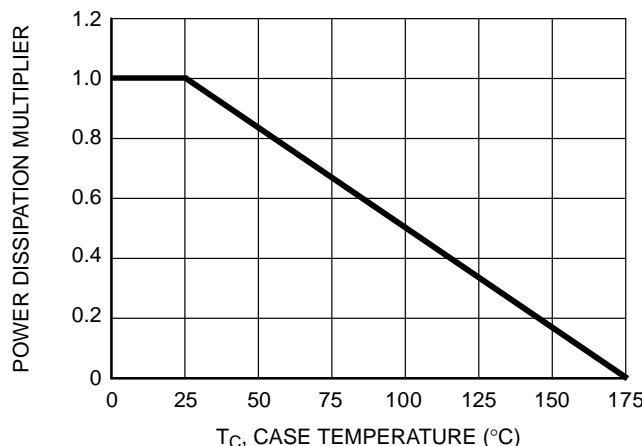


Figure 1. Normalized Power Dissipation vs. Ambient Temperature

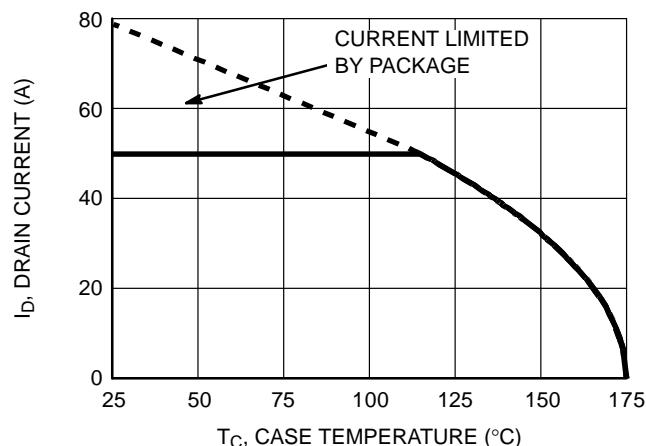


Figure 2. Maximum Continuous Drain Current vs. Case Temperature

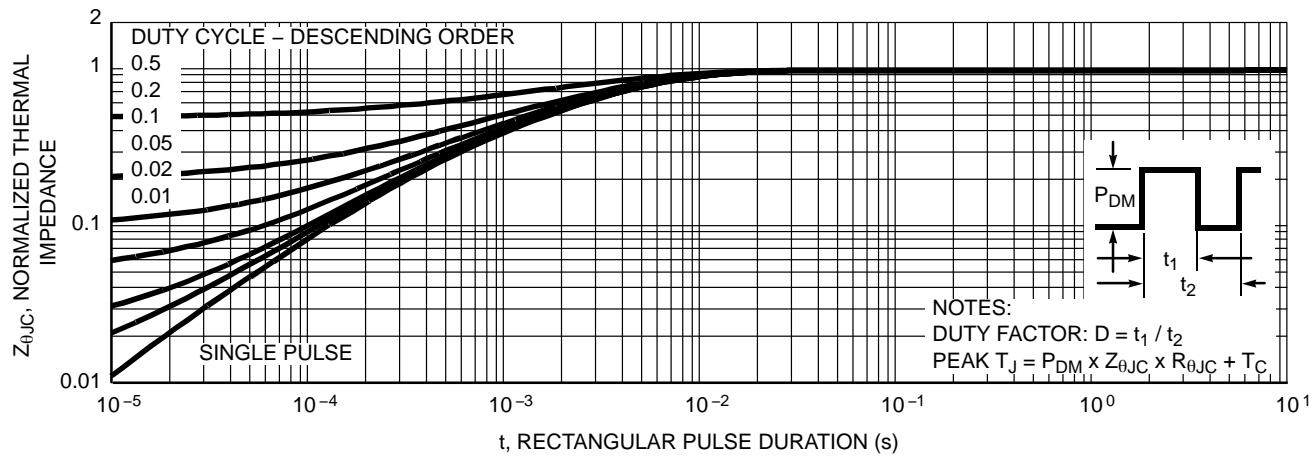


Figure 3. Normalized Maximum Transient Thermal Impedance

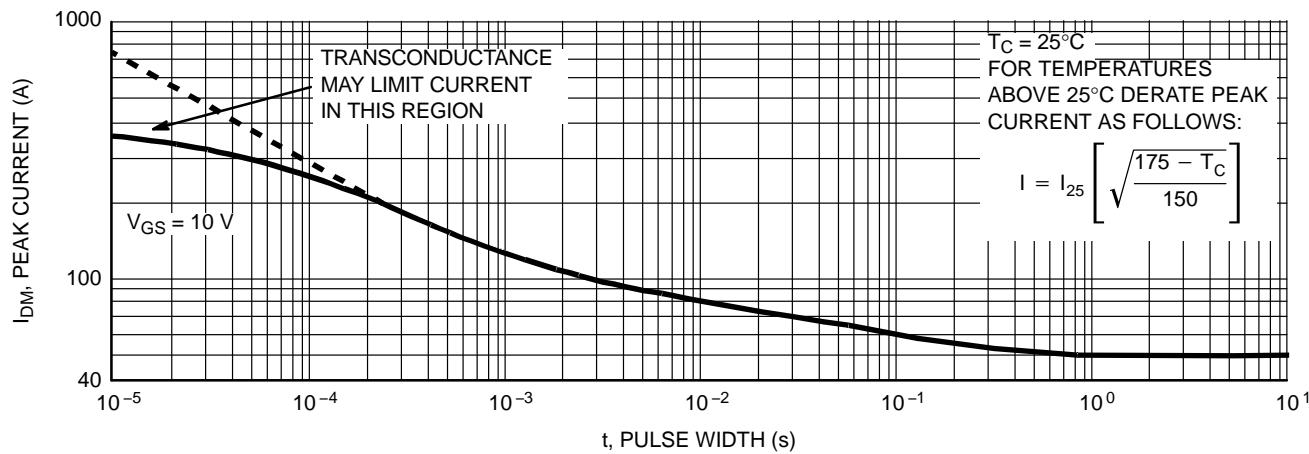


Figure 4. Peak Current Capability

TYPICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$, unless otherwise noted) (continued)

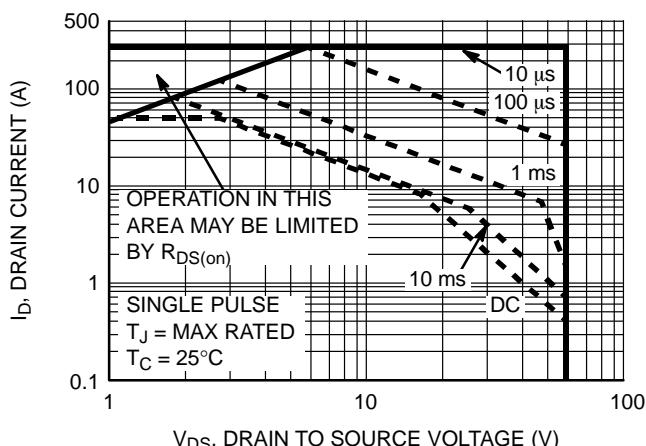
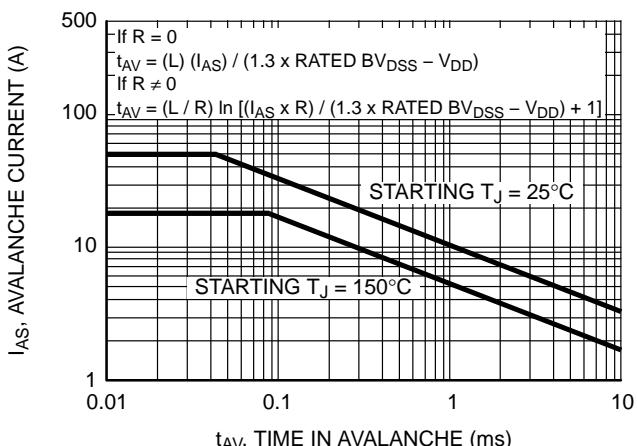


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to **onsemi** Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

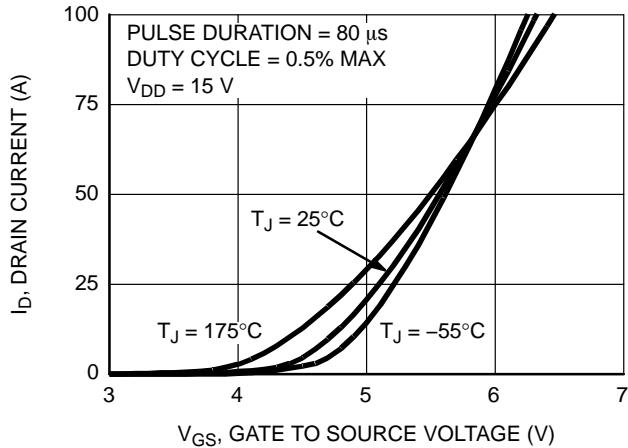


Figure 7. Transfer Characteristics

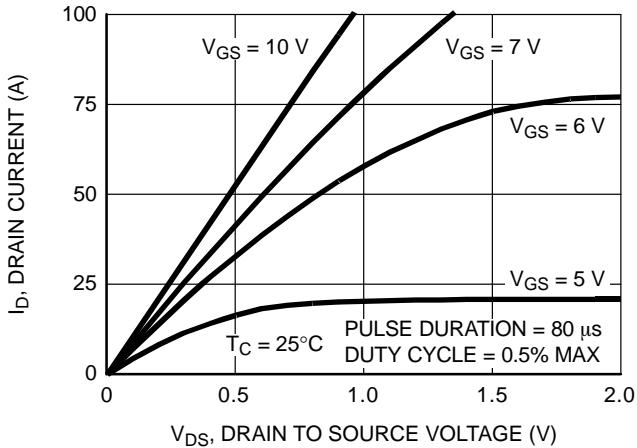


Figure 8. Saturation Characteristics

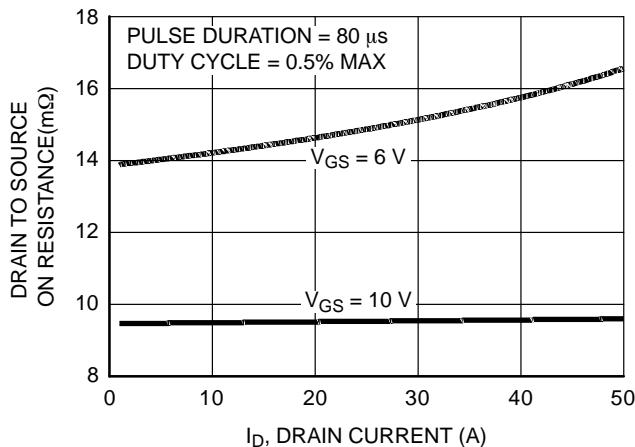


Figure 9. Drain to Source On Resistance vs. Drain Current

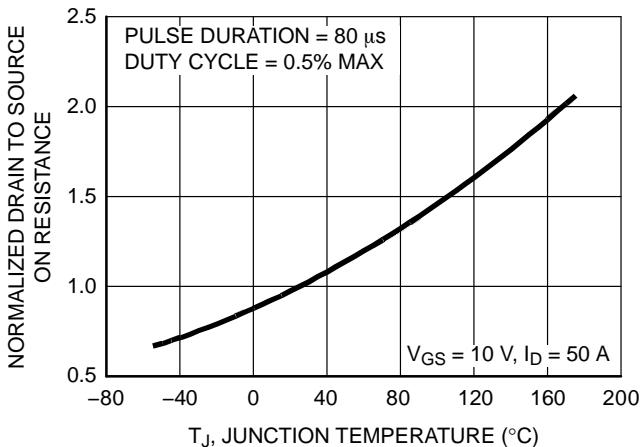


Figure 10. Normalized Drain to Source On Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$, unless otherwise noted) (continued)

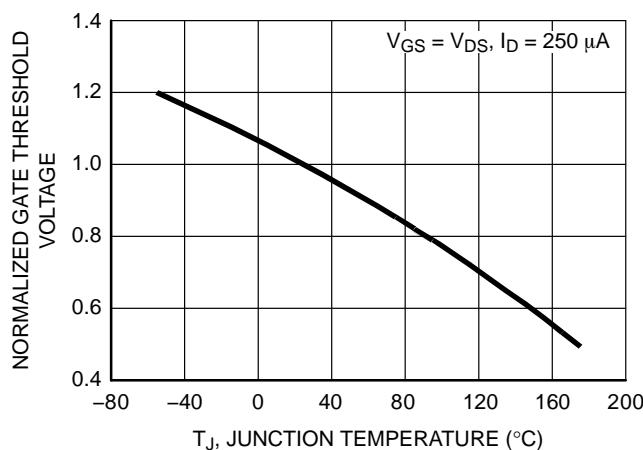


Figure 11. Normalized Gate Threshold Voltage vs. Junction Temperature

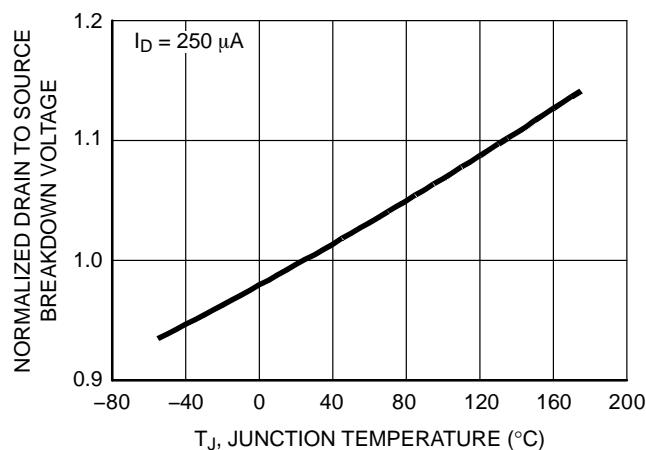


Figure 12. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

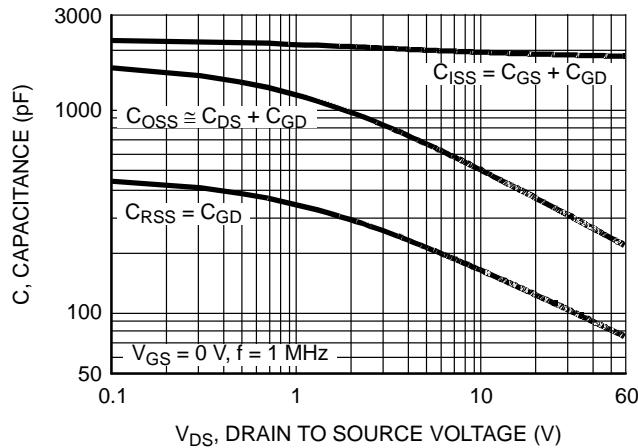


Figure 13. Capacitance vs. Drain to Source Voltage

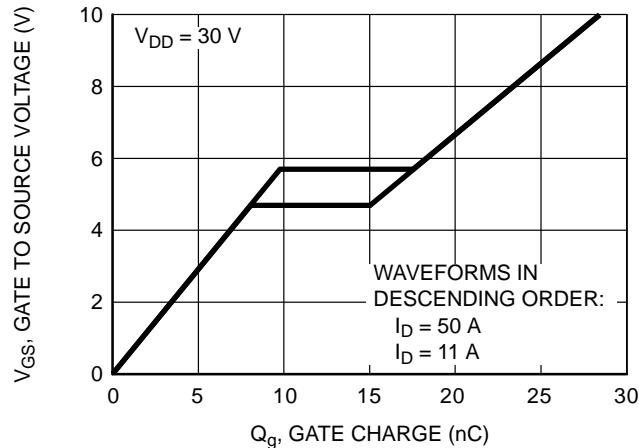


Figure 14. Gate Charge Waveforms for Constant Gate Currents

TEST CIRCUITS AND WAVEFORMS

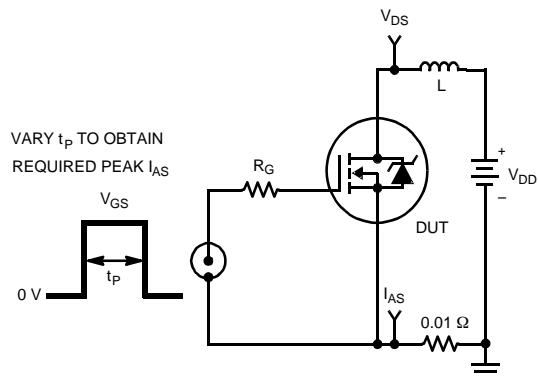


Figure 15. Unclamped Energy Test Circuit

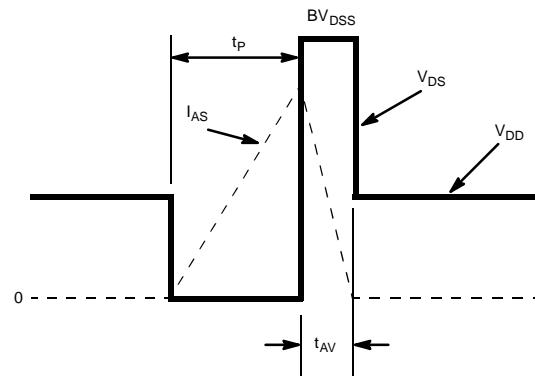


Figure 16. Unclamped Energy Waveforms

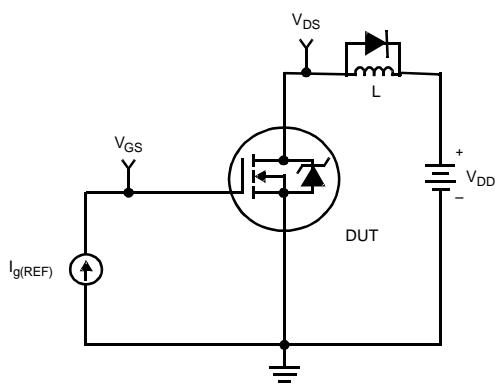


Figure 17. Gate Charge Test Circuit

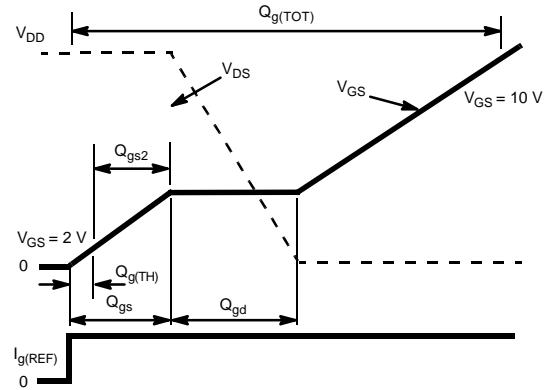


Figure 18. Gate Charge Waveforms

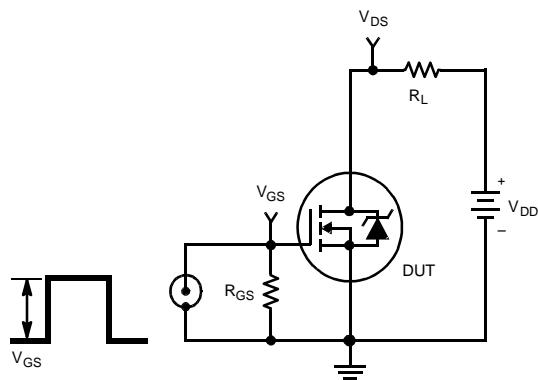


Figure 19. Switching Time Test Circuit

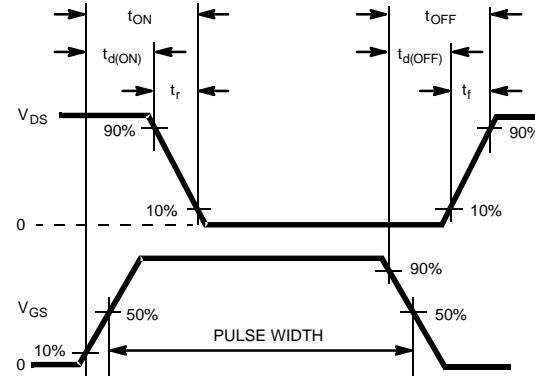


Figure 20. Switching Time Waveforms

THERMAL RESISTANCE VS. MOUNTING PAD AREA

The maximum rated junction temperature, T_{JM} , and the thermal resistance of the heat dissipating path determines the maximum allowable device power dissipation, P_{DM} , in an application. Therefore the application's ambient temperature, T_A (°C), and thermal resistance R_{0JA} (°C/W) must be reviewed to ensure that T_{JM} is never exceeded. Equation 1 mathematically represents the relationship and serves as the basis for establishing the rating of the part.

$$P_{DM} = \frac{(T_{JM} - T_A)}{R_{0JA}} \quad (\text{eq. 1})$$

In using surface mount devices such as the TO-252 package, the environment in which it is applied will have a significant influence on the part's current and maximum power dissipation ratings. Precise determination of P_{DM} is complex and influenced by many factors:

1. Mounting pad area onto which the device is attached and whether there is copper on one side or both sides of the board.
2. The number of copper layers and the thickness of the board.
3. The use of external heat sinks.
4. The use of thermal vias.
5. Air flow and board orientation.
6. For non steady state applications, the pulse width, the duty cycle and the transient thermal response of the part, the board and the environment they are in.

onsemi provides thermal information to assist the designer's preliminary application evaluation. Figure 21 defines the R_{0JA} for the device as a function of the top copper (component side) area. This is for a horizontally positioned FR-4 board with 1 oz copper after 1000 seconds of steady state power with no air flow. This graph provides the necessary information for calculation of the steady state junction temperature or power dissipation. Pulse applications

can be evaluated using the **onsemi** device Spice thermal model or manually utilizing the normalized maximum transient thermal impedance curve.

Thermal resistances corresponding to other copper areas can be obtained from Figure 21 or by calculation using Equation 2 or 3. Equation 2 is used for copper area defined in inches square and Equation 3 is for area in centimeters square. The area, in square inches or square centimeters is the top copper area including the gate and source pads.

$$R_{0JA} = 33.32 + \frac{23.84}{(0.268 + \text{Area})} \quad (\text{eq. 2})$$

Area in Inches Squared

$$R_{0JA} = 33.32 + \frac{154}{(1.73 + \text{Area})} \quad (\text{eq. 3})$$

Area in Centimeters Squared

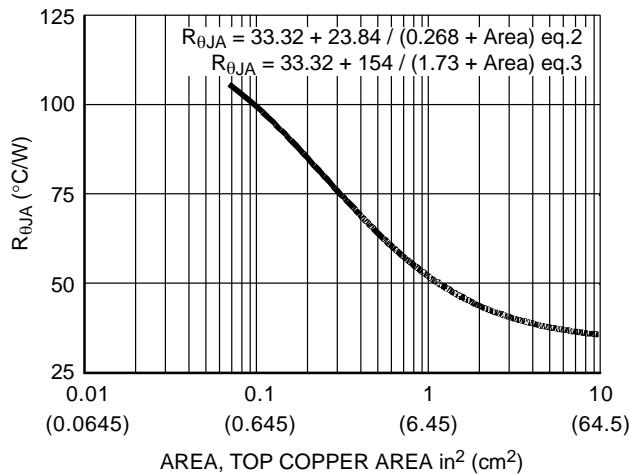


Figure 21. Thermal Resistance vs. Mounting Pad Area

FDD10AN06A0

PSPICE ELECTRICAL MODEL

.SUBCKT FDD10AN06A0 2 1 3 ; rev July 2002

Ca 12 8 7e-10

Cb 15 14 7e-10

Cin 6 8 1.8e-9

Dbody 7 5 DbodyMOD

Dbreak 5 11 DbreakMOD

Dplcap 10 5 DplcapMOD

Ebreak 11 7 17 18 67.2

Eds 14 8 5 8 1

Egs 13 8 6 8 1

Esg 6 10 6 8 1

Evthres 6 21 19 8 1

Evtemp 20 6 18 22 1

It 8 17 1

Lgate 1 9 3.2e-9

Ldrain 2 5 1.0e-9

Lsource 3 7 1.2e-9

RLgate 1 9 32

RLdrain 2 5 10

RLsource 3 7 12

Mmed 16 6 8 8 MmedMOD

Mstro 16 6 8 8 MstroMOD Mweak 16 21 8 8

MweakMOD Rbreak 17 18 RbreakMOD 1

Rdrain 50 16 RdrainMOD 1.35e-3

Rgate 9 20 3.6

RSLC1 5 51 RSLCMOD 1e-6

RSLC2 5 50 1e3

Rsource 8 7 RsourceMOD 6e-3

Rvthres 22 8 RvthresMOD 1

Rvtemp 18 19 RvtempMOD 1

S1a 6 12 13 8 S1AMOD

S1b 13 12 13 8 S1BMOD

S2a 6 15 14 13 S2AMOD

S2b 13 15 14 13 S2BMOD

Vbat 22 19 DC 1

ESLC 51 50 VALUE={(V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)/(1e-6*250),7))}

.MODEL DbodyMOD D (IS=2E-11 N=1.06 RS=3.3e-3 TRS1=2.4e-3 TRS2=1.1e-6

+ CJO=1.25e-9 M=5.3e-1 TT=4.2e-8 XTI=3.9)

.MODEL DbreakMOD D (RS=2.7e-1 TRS1=1e-3 TRS2=-8.9e-6)

.MODEL DplcapMOD D (CJO=4.7e-10 IS=1e-30 N=10 M=0.44)

.MODEL MmedMOD NMOS (VTO=3.5 KP=5.5 IS=1e-30 N=10 TOX=1 L=1u W=1u RG=3.6)

.MODEL MstroMOD NMOS (VTO=4.25 KP=80 IS=1e-30 N=10 TOX=1 L=1u W=1u)

.MODEL MweakMOD NMOS (VTO=2.92 KP=0.03 IS=1e-30 N=10 TOX=1 L=1u W=1u RG=36 RS=0.1)

FDD10AN06A0

```

.MODEL RbreakMOD RES (TC1=9e-4 TC2=5e-7)
.MODEL RdrainMOD RES (TC1=2.5e-2 TC2=7.8e-5)
.MODEL RSLCMOD RES (TC1=1e-3 TC2=3.5e-5)
.MODEL RsourceMOD RES (TC1=1e-3 TC2=1e-6)
.MODEL RvthresMOD RES (TC1=-5.3e-3 TC2=-1.3e-5)
.MODEL RvtempMOD RES (TC1=-2.6e-3 TC2=1.3e-6)

.MODEL S1AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-8 VOFF=-5)
.MODEL S1BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-5 VOFF=-8)
.MODEL S2AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-2 VOFF=-1.5)
.MODEL S2BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-1.5 VOFF=-2)
.ENDS

```

NOTE: For further discussion of the PSPICE model, consult *A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options*; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.

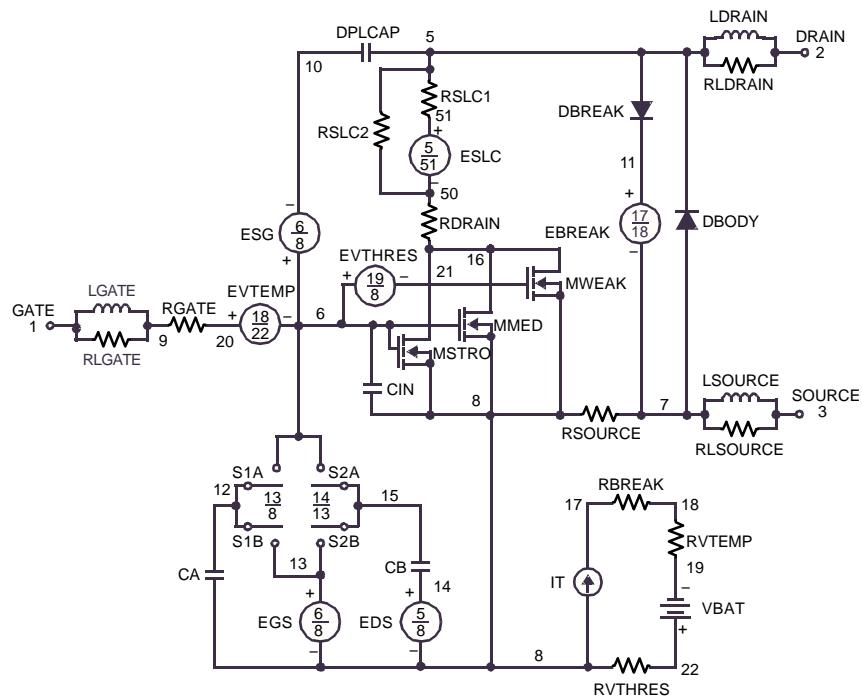


Figure 22.

FDD10AN06A0

SABER ELECTRICAL MODEL

REV July 2002

```
template FDD10AN06A0 n2,n1,n3
electrical n2,n1,n3
{
var i iscl
dp..model dbodymod = (isl=2e-11, nl=1.06, rs=3.3e-3, trs1=2.4e-3, trs2=1.1e-6, cjo=1.25e-9, m=5.3e-1, tt=4.2e-8, xti=3.9)
dp..model dbreakmod = (rs=2.7e-1, trs1=1e-3, trs2=-8.9e-6)
dp..model dplcapmod = (cjo=4.7e-10, isl=10e-30, nl=10, m=0.44)
m..model mmedmod = (type=_n, vto=3.5, kp=5.5, is=1e-30, tox=1)
m..model mstrongmod = (type=_n, vto=4.25, kp=80, is=1e-30, tox=1)
m..model mweakmod = (type=_n, vto=2.92, kp=0.03, is=1e-30, tox=1, rs=0.1) sw_vcsp..model s1amod =
(ron=1e-5, roff=0.1, von=-8, voff=-5)
sw_vcsp..model s1bmod = (ron=1e-5, roff=0.1, von=-5, voff=-8)
sw_vcsp..model s2amod = (ron=1e-5, roff=0.1, von=-2, voff=-1.5)
sw_vcsp..model s2bmod = (ron=1e-5, roff=0.1, von=-1.5, voff=-2)
c.ca n12 n8 = 7e-10
c.cb n15 n14 = 7e-10
c.cin n6 n8 = 1.8e-9

dp.dbody n7 n5 = model=dbodymod
dp.dbreak n5 n11 = model=dbreakmod
dp.dplcap n10 n5 = model=dplcapmod

spe.ebreak n11 n7 n17 n18 = 67.2
spe.eds n14 n8 n5 n8 = 1
spe.egs n13 n8 n6 n8 = 1
spe.esg n6 n10 n6 n8 = 1
spe.evthres n6 n21 n19 n8 = 1
spe.evtemp n20 n6 n18 n22 = 1

i.it n8 n17 = 1

l.lgate n1 n9 = 3.2e-9
l.ldrain n2 n5 = 1.0e-9
l.lsource n3 n7 = 1.2e-9

res.rlgate n1 n9 = 32
res.rldrain n2 n5 = 10
res.rlsource n3 n7 = 12

m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u
m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u
m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u

res.rbreak n17 n18 = 1, tc1=9e-4, tc2=5e-7
res.rdrain n50 n16 = 1.35e-3, tc1=2.5e-2, tc2=7.8e-5
res.rgate n9 n20 = 3.6
res.rslc1 n5 n51 = 1e-6, tc1=1e-3, tc2=3.5e-5
res.rslc2 n5 n50 = 1e3
res.rsource n8 n7 = 6e-3, tc1=1e-3, tc2=1e-6
res.rvthres n22 n8 = 1, tc1=-5.3e-3, tc2=-1.3e-5
res.rvtemp n18 n19 = 1, tc1=-2.6e-3, tc2=1.3e-6
sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod
sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod
sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod
```

FDD10AN06A0

sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod

```
v.vbat n22 n19 = dc=1
equations {
i (n51->n50) +=iscl
iscl: v(n51,n50) = ((v(n5,n51)/(1e-9+abs(v(n5,n51))))*((abs(v(n5,n51)*1e6/250))** 7))
}
```

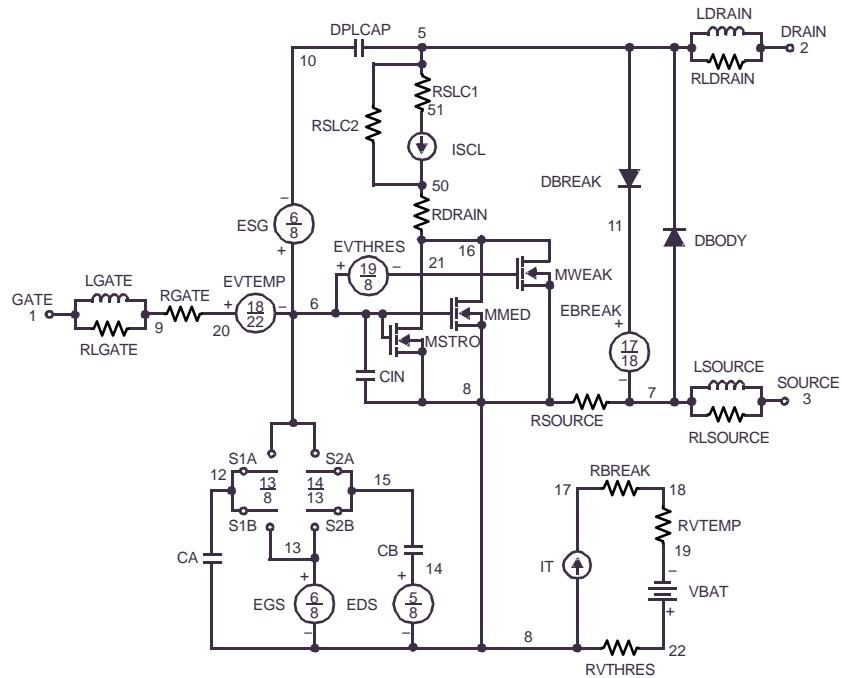


Figure 23.

FDD10AN06A0

SPICE ELECTRICAL MODEL

REV 23 July 2002
FDD10AN06A0T

CTHERM1 TH 6 3.2e-3
CTHERM2 6 5 3.3e-3
CTHERM3 5 4 3.4e-3
CTHERM4 4 3 3.5e-3
CTHERM5 3 2 6.4e-3
CTHERM6 2 TL 1.9e-2

RTERM1 TH 6 5.5e-4
RTERM2 6 5 5.0e-3
RTERM3 5 4 4.5e-2
RTERM4 4 3 1.5e-1
RTERM5 3 2 3.37e-1
RTERM6 2 TL 3.5e-1

SABER ELECTRICAL MODEL

SABER thermal model FDD10AN06A0T

```
template thermal_model th tl
thermal_c th, tl
{
  ctherm.cterm1 th 6 =3.2e-3
  ctherm.cterm2 6 5 =3.3e-3
  ctherm.cterm3 5 4 =3.4e-3
  ctherm.cterm4 4 3 =3.5e-3
  ctherm.cterm5 3 2 =6.4e-3
  ctherm.cterm6 2 tl =1.9e-2
```

```
rterm.rterm1 th 6 =5.5e-4
rterm.rterm2 6 5 =5.0e-3
rterm.rterm3 5 4 =4.5e-2
rterm.rterm4 4 3 =1.5e-1
rterm.rterm5 3 2 =3.37e-1
rterm.rterm6 2 tl =3.5e-1
}
```

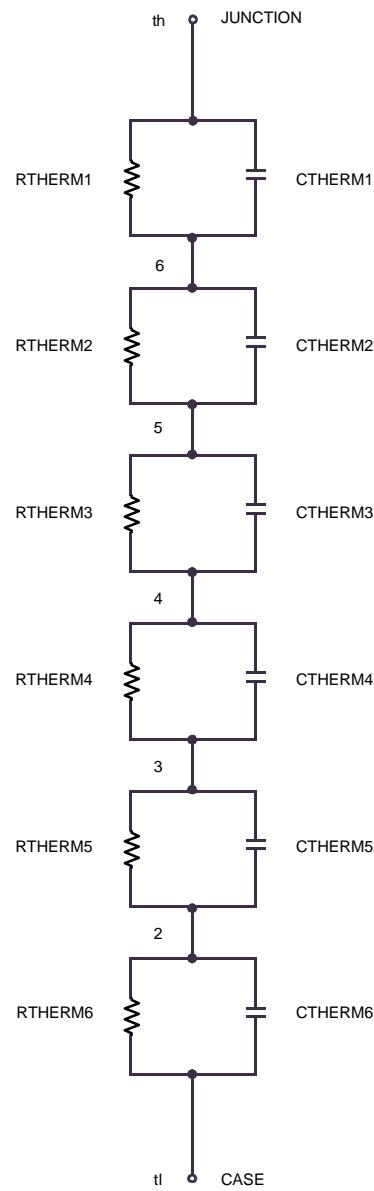


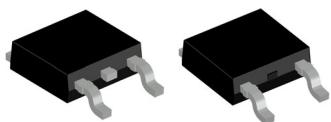
Figure 24.

ORDERING INFORMATION

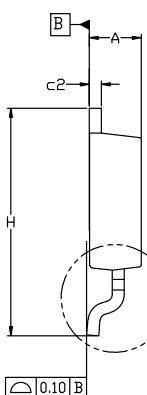
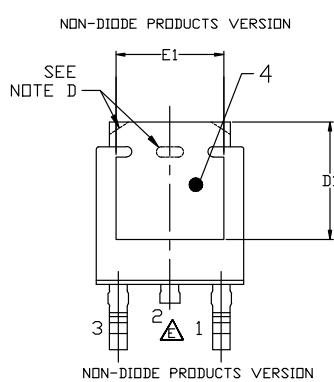
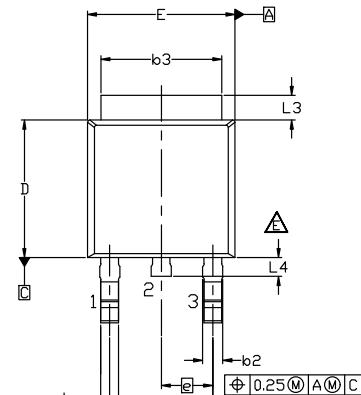
| Device | Device Marking | Package | Reel Size | Tape Width | Shipping [†] |
|-------------|----------------|---|-----------|------------|-----------------------|
| FDD10AN06A0 | FDD10AN06A0 | DPAK3 (TO-252 3 LD) (Pb-Free, Halide Free) | 330 mm | 16 mm | 2500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

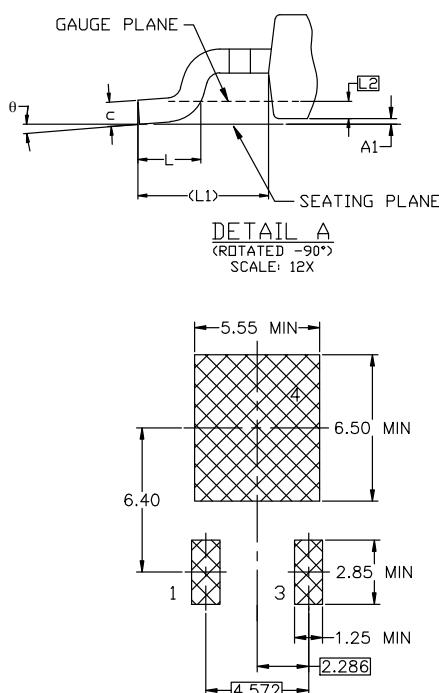
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DPAK3 6.10x6.54x2.29, 4.57P
CASE 369AS
ISSUE B

DATE 20 DEC 2023



NOTES: UNLESS OTHERWISE SPECIFIED
A) THIS PACKAGE CONFORMS TO JEDEC, TD-252,
ISSUE F, VARIATION AA.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONING AND TOLERANCING PER
ASME Y14.5M-2018.
D) SUPPLIER DEPENDENT MOLD LOCKING HOLES OR CHAMFERED
CORNERS OR EDGE PROTRUSION.
E) FOR DIODE PRODUCTS, L4 IS 0.25 MM MAX PLASTIC BODY
STUB WITHOUT CENTER LEAD.
F) DIMENSIONS ARE EXCLUSIVE OF BURRS,
MOLD FLASH AND TIE BAR EXTRUSIONS.
G) LAND PATTERN RECOMMENDATION IS BASED ON IPC7351A STD
TD228P991X239-3N.



| DIM | MILLIMETERS | | |
|-----|-------------|------|-------|
| | MIN. | NOM. | MAX. |
| A | 2.18 | 2.29 | 2.39 |
| A1 | 0.00 | — | 0.127 |
| b | 0.64 | 0.77 | 0.89 |
| b2 | 0.76 | 0.95 | 1.14 |
| b3 | 5.21 | 5.34 | 5.46 |
| c | 0.45 | 0.53 | 0.61 |
| c2 | 0.45 | 0.52 | 0.58 |
| D | 5.97 | 6.10 | 6.22 |
| D1 | 5.21 | — | — |
| E | 6.35 | 6.54 | 6.73 |
| E1 | 4.32 | — | — |
| e | 2.286 | BSC | |
| e1 | 4.572 | BSC | |
| H | 9.40 | 9.91 | 10.41 |
| L | 1.40 | 1.59 | 1.78 |
| L1 | 2.90 | REF | |
| L2 | 0.51 | BSC | |
| L3 | 0.89 | 1.08 | 1.27 |
| L4 | — | — | 1.02 |
| θ | 0° | — | 10° |

LAND PATTERN RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR
PB-FREE STRATEGY AND SOLDERING DETAILS,
PLEASE DOWNLOAD THE ON SEMICONDUCTOR
SOLDERING AND MOUNTING TECHNIQUES
REFERENCE MANUAL, SOLDERRM/D.

**GENERIC
MARKING DIAGRAM***


XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Assembly Lot Code

| | | |
|------------------|-----------------------------|---|
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